

secondly, feeding a nitrous oxide (N<sub>2</sub>O) gas into a reactor;

thirdly, generating a plasma in said reactor; and

fourthly, removing a portion of said organic compound to generate said organic plug within said via.

OC.  
5/2/2005

**Claim 16 (currently amended).** The method of claim <sup>15</sup>~~16~~ further comprising generating a gas mixture by mixing a diluent with said N<sub>2</sub>O gas ~~said N<sub>2</sub>O gas~~, and applying said gas mixture to said reactor.

**Claim 17 (original).** The method of claim 16 wherein said diluent is a noble gas.

**Claim 18 (original).** The method of claim 16 wherein said silicon containing dielectric material is selected from a group consisting of organosilicate glass (OSG), silicon dioxide (SiO<sub>2</sub>), and fluorinated silicate glass (FSG).

**Claim 19 (original).** The method of claim 18 wherein said method for generating said organic plug is applied during one of a plurality of steps performed during a dual damascene process.